Fuse Datasheet

157 Series Standard Nano^{2®} Fuse and Clip Assembly





Additional Information



Samples

Description

The 157 Series – Standard Nano Fuse/Clip assembly is a small, square, very fast-acting surface mount fuse that is assembled in surface mountable fuse clips. The fuse clip and pre-installed fuse combination can be automatically placed in PC Board in one efficient manufacturing operation. It permits quick and easy replacement of fuses without performing desoldering process, even in the field and without exposing the PC Board to detrimental effects of rework solder heat.

Features & Benefits

- Surface Mountable
- Very Fast-Acting Fuse
- Fully compatible with RoHS/ Pb-Free solder alloys and higher temperature profiles associated with leadfree assembly.

Applications

- Instrumentation
- Base Stations

- Easily replaceable on PC Board (Field Replaceable)
- RoHS compliant and Halogen Free
- Available in ratings of 0.062 ~ 10 Amperes.
- Telecommunications

Electrical Characteristics for Series

% of Ampere Rating	Opening Time at 25°C	
100%	4 hours Minimum	
200%	5 secs. Maximum	

Electrical Specifications by Item

Ampere Rating (A)	Amp Code	Max Voltage Rating (V)	Interrupting Rating (A)	Fuse Nominal Cold Furnished Resistance (Ohms)	Nominal Cold	Nominal	Agency Approvals	
					Resistance (Ohms)	Melting I ² t (A ² sec)	c RL ° us	PSE
0.062	0.062	125		451.062	5.5372	0.00019	Х	-
0.08	0.08	125		451.08	4.0500	0.00033	Х	-
0.1	0.1	125		451.1	3.1000	0.00138	Х	-
0.125	0.125	125		451.125	1.7059	0.00286	Х	-
0.16	0.16	125		453.16	1.2157	0.0048	Х	-
0.2	0.2	125		453.2	1.3971	0.00652	Х	-
0.25	0.25	125		453.25	1.0496	0.01126	Х	-
0.315	0.315	125		453.315	0.3881	0.0311	Х	-
0.375	0.375	125		453.375	0.4518	0.0442	Х	-
0.4	0.4	125		453.4	0.4212	0.0551	Х	-
0.5	0.5	125		453.5	0.3031	0.0824	Х	-
0.63	0.63	125	50A @ 125 VAC/VDC	453.63	0.2012	0.1381	Х	-
0.75	0.75	125		453.75	0.1437	0.2143	Х	-
0.8	0.8	125		453.8	0.1348	0.2654	Х	-
1.0	1.0	125		453001.0	0.0776	0.6029	Х	Х
1.25	1.25	125	300A @ 32 VDC	4531.25	0.078	0.664	Х	Х
1.5	1.5	125		45301.5	0.0634	0.853	Х	Х
1.6	1.6	125		45301.6	0.0580	1.06	Х	Х
2.0	2.0	125		453002.0	0.0373	0.53	Х	Х
2.5	2.5	125		45302.5	0.0288	1.029	Х	Х
3.0	3.0	125		453003.0	0.0229	1.65	Х	Х
3.15	3.15	125		4533.15	0.0215	1.92	Х	Х
3.5	3.5	125		45303.5	0.0203	2.469	Х	Х
4.0	4.0	125		453004.0	0.0163	3.152	Х	Х
5.0	5.0	125		453005.0	0.0127	5.566	Х	Х
6.3	6.3	125		45306.3	0.0098	9.17	Х	Х
7.0	7.0	125		453007.0	0.0092	10.32	X	Х
8.0	8.0	125		453008.0	0.0079	20.23	X	X
10.0	10.0	125	35A @ 125 VAC / 50A @125 VDC 300A @ 32VDC	453010.0	0.0058	26.46	Х	Х

Contresistance measured at less than 10% of lated
 l²t values stated for 8ms opening time.

3. Agency Approval Table Key: X=Approved or Certified, P=Pending and Blank=Not Approved



options.

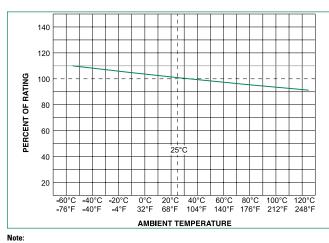
Fuse Datasheet

Agency Approvals

Agency	Agency File Number	Ampere Range
c 🔊 us	E14721	0.062A - 10A
	NBK030205-E10480A NBK030205-E10480B NBK101105-E184655	1A - 1.6A 2A - 5A 6.3A - 10A

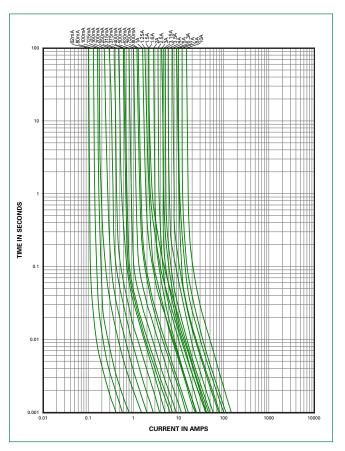
Note: PSE/METI Certification is only applicable to the fuse. Clips do not require certification for the Japanese Market.

Temperature Re-rating Curve



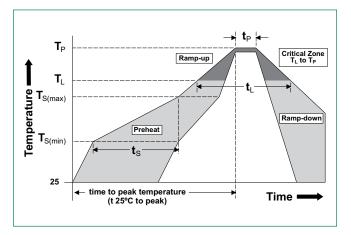
1. Rerating depicted in this curve is in addition to the standard derating of 25% for continuous operation.

Average Time Current Curves



Reflow Condition Pb - Free assembly - Temperature Min (T_{s(min)}) 150°C Pre Heat - Temperature Max (T_{s(max)}) 200°C - Time (Min to Max) (t_s) 60 - 180 secs Average ramp up rate (Liquidus Temp (T,) to 5°C/second max. peak $T_{S(max)}$ to T_L - Ramp-up Rate 5°C/second max. 217°C - Temperature (T_L) (Liquidus) Reflow - Temperature (t,) 60 - 150 seconds 260^{+0/-5} °C Peak Temperature (T_P) Time within 5°C of actual peak Temperature (t,) 20 - 40 seconds 5°C/second max. **Ramp-down Rate** Time 25°C to peak Temperature (T_P) 8 minutes max. Do not exceed 260°C

Soldering Parameters

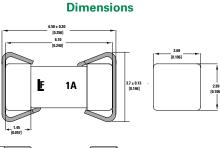


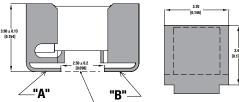
MLittelfuse

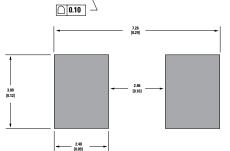
Product Characteristics

Materials	 Body: Ceramic Cap: For 0.062A ~ 0.125A – Au plated Brass For 0.200A ~ 10A – Silver plated Brass Clip Plating: Matte Tin 	
Product Marking Body: Brand Logo, Current Rating		
Clip Retention	Force applied at fuse center, perpendicular to the long axis (@ 0.75 lbs. MIN)	
Solderability	MIL-STD-202, Method 208 / IPC/ EIA / JEDEC J-STD-002, Test Condition A	
Humidity Test	MIL –STD-202, Method 103 @ 85°C / 85%RH, 1000 hours	
Resistance to Solvents	MIL-STD-202, Method 215 (3 solvent types)	

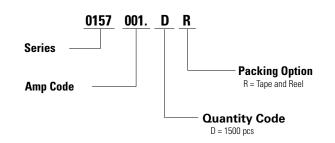
Operating Temperature	-55°C to 125°C with proper derating		
	MIL-STD-202, Method 107,		
Thermal Shock	Test Condition B		
	(5 cycles -65°C to +125°C)		
Vibration	MIL-STD-202, Method 201		
Vibration	(10-55 Hz)		
Moisture Resistance	MIL-STD-202, Method 106,		
Woisture Resistance	10 cycles		
	MIL-STD-202, Method 101,		
Salt Spray/ Atmosphere	Test Condition B (48 hrs.),		
	5% NaCl in De-ionized Water		
	MIL-STD-202, Method 213,		
Shock	Test Condition I (100 G's peak for 6		
	milliseconds)		







Part Numbering System



Packaging

Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code	
Tape and Reel	Surface Mount	1500	DR	

PCB Recommendation for Thermal Management 1. Minimum Copper Layer Thickness = 100um

1. Minimum Copper Layer Thickness = 100um 2. Minimum Copper Trace Width = 10mm

2. Minimu Note:

Alternate methods of thermal management may be used. In such cases, under normal operations, the maximum temperature of the fuse body should not exceed 80°C in a 25°C ambient environment.

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